

Title (en)

CIRCUIT BOARD ARRANGEMENT FOR THERMALLY STRESSED ELECTRONIC COMPONENTS, IN PARTICULAR IN MOTOR VEHICLE CONTROL APPARATUS

Title (de)

LEITERPLATTENANORDNUNG FÜR THERMISCH BELASTETE ELEKTRONISCHE BAUELEMENTE, INSBESONDERE IN KRAFTFAHRZEUGSTEUERGERÄTEN

Title (fr)

AGENCEMENT DE CARTE À CIRCUITS IMPRIMÉS POUR COMPOSANTS ÉLECTRONIQUES SOLlicitÉS THERMIQUEMENT, EN PARTICULIER DANS DES APPAREILS DE COMMANDE DE VÉHICULES AUTOMOBILES

Publication

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Application

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Priority

- EP 2009056359 W 20090526
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- DE 102009022110 A 20090520

Abstract (en)

[origin: WO2009144215A1] Circuit board arrangement, in particular multiple layer circuit board arrangement (16) with at least one low-power circuit path, wherein the circuit board arrangement is suitable for population with at least one electronic circuit board element to be cooled, wherein the circuit board consisting of a nonconductive material comprises at least one cooling inlay (22, 21, 22') embedded in the circuit board for cooling of the power component, wherein the cooling inlay forms at least in part, a high power guide element for the at least one electronic power component, wherein the line cross section or the power carry capacity of the high power guide element is significantly greater than the line cross section or the current carry capacity of the low power circuit path, and wherein the high power guide element is used and/or is also used for electrical contacting of the power component.

IPC 8 full level

H05K 1/02 (2006.01)

CPC (source: EP US)

H05K 1/0204 (2013.01 - EP US); **H05K 1/0263** (2013.01 - EP US); **H05K 2201/10416** (2013.01 - EP US); **Y10T 29/4913** (2015.01 - EP US)

Citation (search report)

See references of WO 2009144215A1

Cited by

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